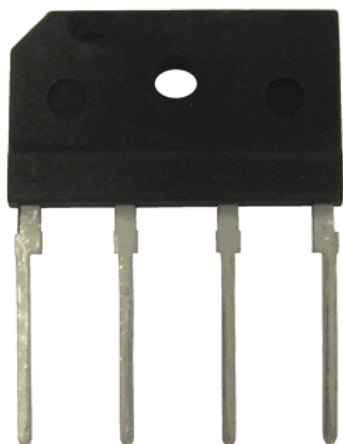


Glass Passivated Single Phase Bridge Rectifiers

Reverse Voltage 200 to 1000V

Forward Current 10 Amp

Features

- Glass passivated die construction
- Ideal for printed circuit boards
- Plastic material used carries UL flammability recognition 94V-0
- High surge current capability
- High temperature soldering guaranteed: 265°C /10 seconds, 0.375" (9.5mm) lead length, 5lbs. (2.3kg) tension

Mechanical Data

Case: Molded plastic case

Terminals: Plated leads solderable per MIL-STD-750, Method 2026

Polarity: Marked on Body

Mounting Position: Any

Module Type

TYPE	V _{RRM}	V _{RSM}
SKBJ10D	200V	300V
SKBJ10G	400V	500V
SKBJ10J	600V	700V
SKBJ10K	800V	900V
SKBJ10M	1000V	1100V

Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted)

Symbol	Conditions	Values	Units
I _{F(AV)}	Maximum average forward output rectified current T _c = 50°C	10	A
I _{FSM}	Peak forward surge current single half sine-wave superimposed on rated load (JEDEC Method)	180	A
i ² t	Rating for fusing (t < 8.3ms)	134	A ² s
Visol	a.c. 50HZ; r.m.s.; 1min	2500	V
R _{θJA} R _{θJC}	Maximum thermal resistance per leg	26 ⁽¹⁾ 5.0 ⁽²⁾	°C/W
T _j , T _{STG}	Operating Junction and storage temperature range	-55 to +150	°C
Weight	Approximate Weight	4.0	g

Electrical Characteristics (TA = 25°C unless otherwise noted)

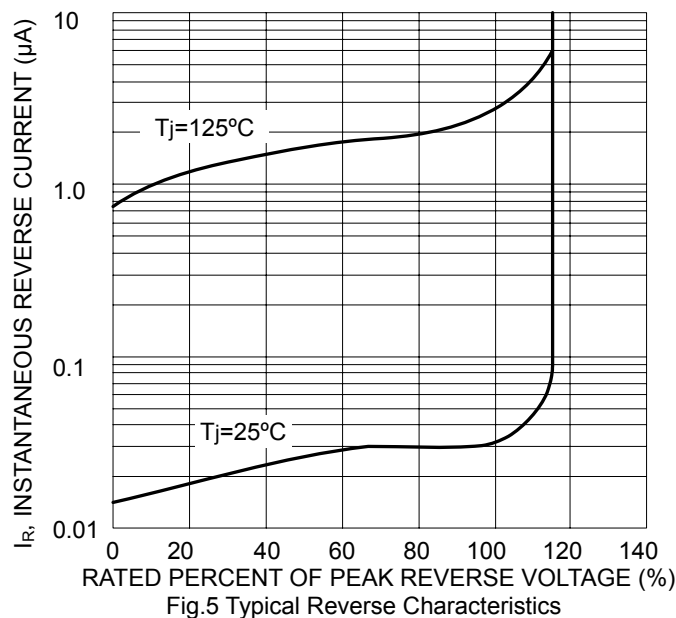
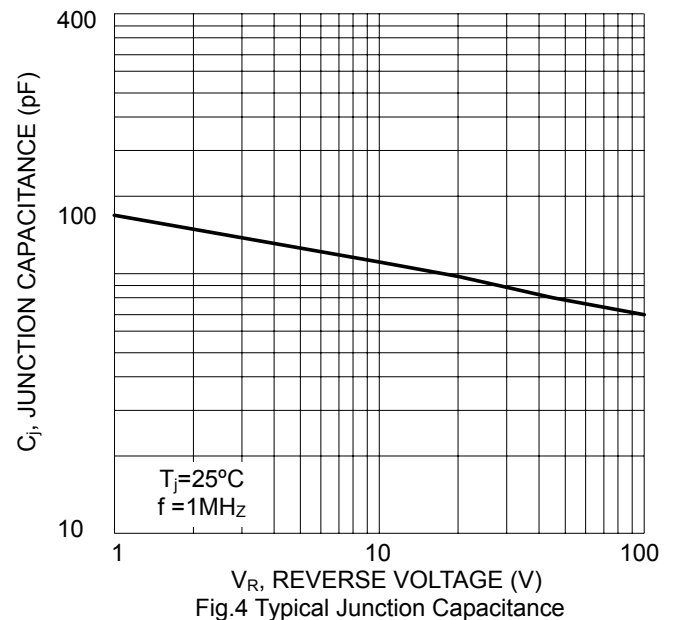
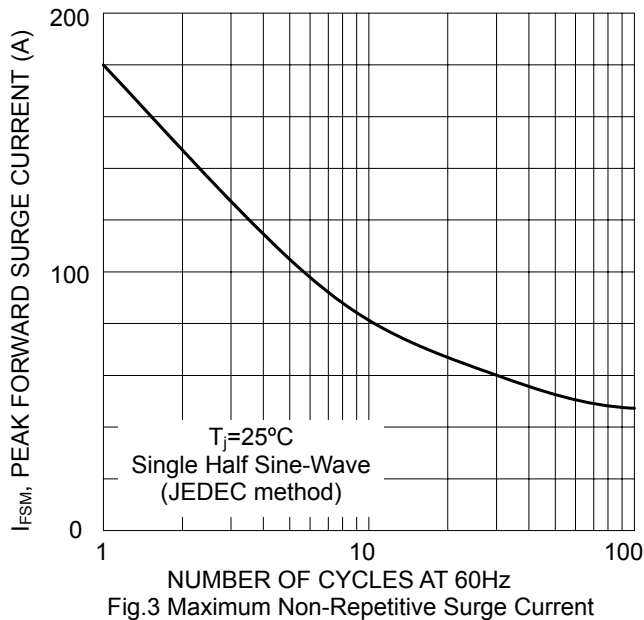
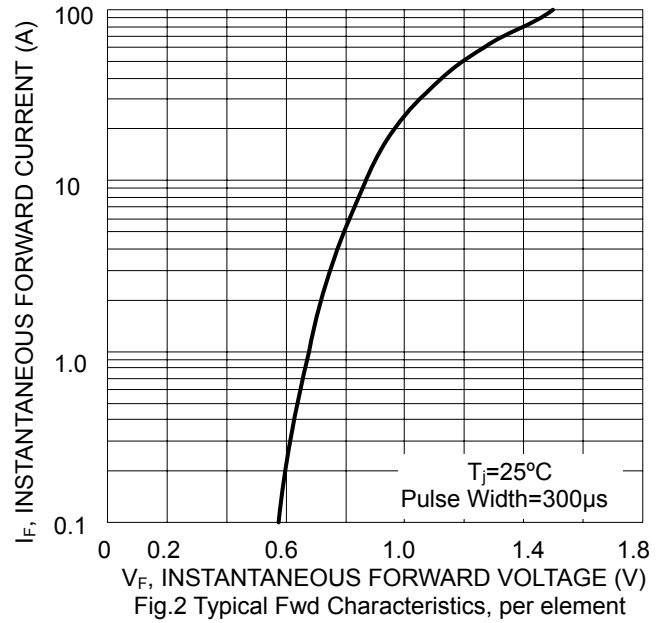
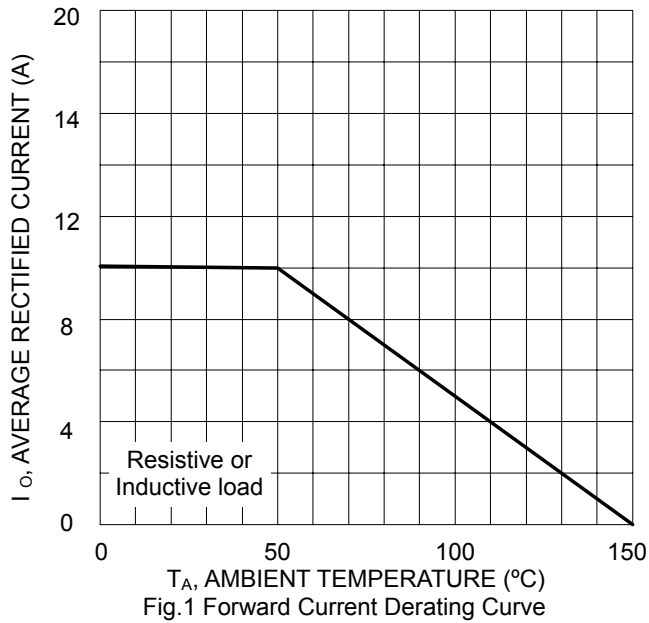
Symbol	Conditions	Values	Units
V _F	Maximum Instantaneous Forward Voltage per leg I _{FM} = 5.0A	1.05	V
I _R	Maximum DC reverse current at rated DC blocking voltage per leg T _A = 25°C T _A = 125°C	5.0 500	μA

Notes: (1) Junction to ambient without heatsink

(2) Junction to case with heatsink

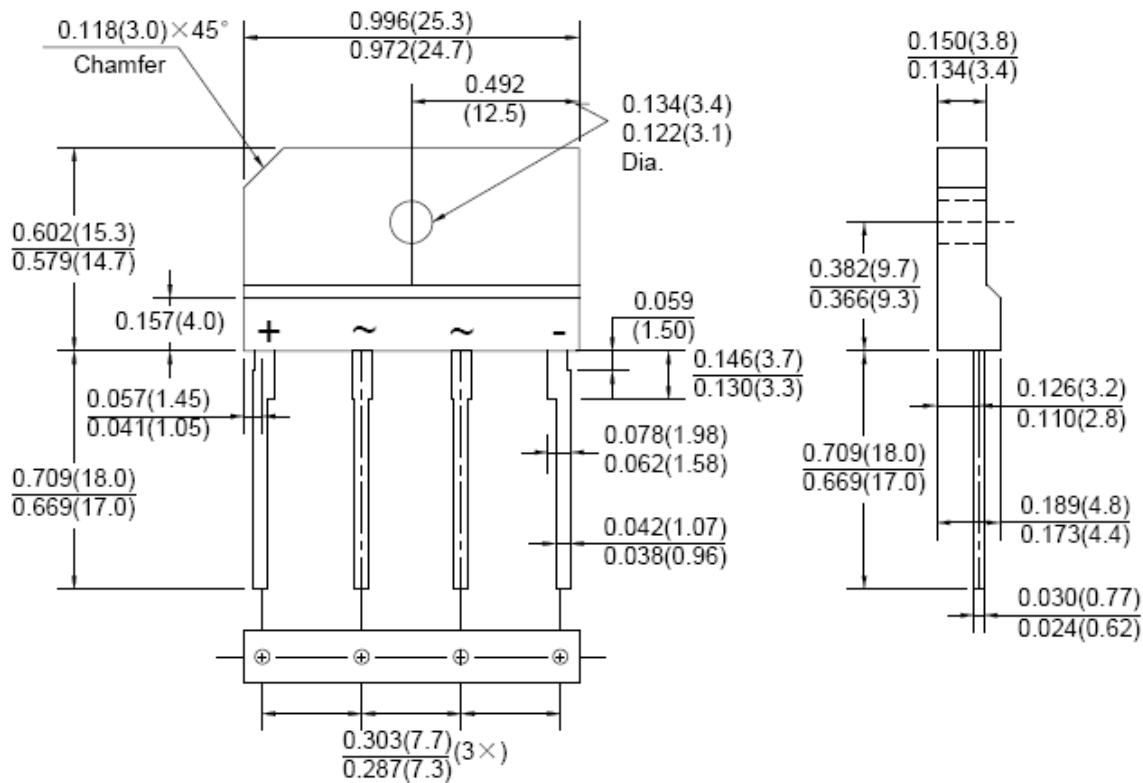
(3) Recommended mounting position is to bolt down on heatsink with silicone thermal compound for maximum heat transfer with M3 screw

Performance Curves



Package Outline Information

CASE: KBJ



Dimensions in inches (mm)